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(54) MODULAR HEAT DISSIPATING DEVICE

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(57) ABSTRACT

A modular heat dissipating device comprising multiple U-shaped fins connected to one another. Each fin includes an upper plate extending from an upper edge of the fin. At least one aperture is defined in the upper plate. A Y-shaped connector extends from the upper edge of the fin within the at least one aperture in the upper plate to engage with the at least one aperture in the upper edge of an adjacent fin. The Y-shaped connector has a leg connected to the upper edge of the fin and two wings extending beyond the edge of the upper plate. A lower plate extends from a lower edge of the fin and has at least one aperture defined in the lower plate. AY-shaped connector extends from the lower edge of the fin within the at least one aperture in the lower plate to engage with the at least one aperture in the lower edge of an adjacent fin. The Y-shaped connector within the at least one aperture in the lower plate has a leg connected to the lower edge of the fin and two wings extending slightly beyond the edge of the lower plate.

4 Claims, 6 Drawing Sheets

